## XP-002342498

## (C) WPI / DERWENT

AN - 1998-114878 [11]

AP - JP19960158343 19960619

**CPY - POPL** 

DC - A23 A25 E14 E36

DR - 1894-U

FS - CPI

IC - C08K13/02 : C08L59/00

MC - A05-H02 A08-A04 A08-A06 E10-E02D2 E10-E02U E31-Q

M3 - [01] B105 B713 B720 B803 B831 C101 C108 C800 C802 C804 C805 C807 M411 M782 M903 M904 M910 Q120 Q130 R038; R01894-M; 1894-U

- [02] G017 G019 G100 H4 H404 H444 H8 J0 J014 J2 J273 M210 M214 M233 M240 M283 M312 M315 M321 M323 M332 M334 M342 M344 M372 M382 M383 M391 M393 M414 M510 M520 M533 M540 M782 M903 M904 Q120 Q130 R038; R05344-M

PA - (POPL) POLYPLASTICS KK

PN - JP10001592 A 19980106 DW199811 C08L59/00 005pp

PR - JP19960158343 19960619

XA - C1998-038055

XIC - C08K-013/02; C08L-059/00; (C08L-059/00 C08L-077/00); (C08L-033/26 C08L-059/00); (C08L-059/00 C08L-075/04); (C08K-003/38 C08K-005/13 C08K-013/02)

- AB J10001592 A polyoxymethylene (POM) composition comprises (a) 100 parts weight (pts. wt.) POM; (b) 0.01-3 pts. wt. sterically hindered phenolic type antioxidant; (c) 0.001-3 pts. wt. nitrogen-containing high molecular weight polymer; and (d) 0.001-3 pts. wt. boric acid compound.
  - Preferably (c) is polyamide (co)polymer or a crosslinked compound of (meth)acrylamide and/or polyurethane. (d) is orthoboric acid, metaboric acid, tetraboric acid and/or diboric trioxide.
  - USE The POM composition is suitable for mouldings.
  - ADVANTAGE The composition has improved heat stability, especially hue stability without inhibiting the heat stability of POM, and good moulding processing properties.

- (Dwg.0/0)

C - C08L59/00 C08L77/00 :

- C08L59/00 C08L33/26:
- C08L59/00 C08L75/04 :
- C08K13/02 C08K3/38 C08K5/13

CN - R01894-M R05344-M

DRL - 1894-U

IW - POLYOXYMETHYLENE COMPOSITION MOULD COMPRISE POLYOXYMETHYLENE STERIC

HINDERED PHENOLIC TYPE ANTIOXIDANT NITROGEN CONTAIN HIGH MOLECULAR WEIGHT COMPOUND BORIC ACID COMPOUND

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HINDERED PHENOLIC TYPE ANTIOXIDANT NITROGEN CONTAIN HIGH MOLECULAR WEIGHT COMPOUND BORIC ACID COMPOUND

NC - 001

OPD - 1996-06-19

ORD - 1998-01-06

PAW - (POPL ) POLYPLASTICS KK

 TI - Polyoxymethylene composition for mouldings - comprises polyoxymethylene, sterically hindered phenolic type antioxidant, nitrogen-containing high molecular weight compound and boric acid compound

A01 - [001] 018; R00001 G1503 D01 D50 D81 F22; H0000; P1887 P0248 P0226 D01 D10 D11 F24; S9999 S1434;

BNSDCCID: <XP 2342498A 1.>

- [002] 018; ND04; B9999 B4682 B4568; B9999 B4262 B4240; B9999 B3623 B3554;
- [003] 018; D01 D19 D18 D76 F30-R; R05344 D01 D11 D10 D19 D18 D34 D50 D63 D76 D95 F33 F30 F41 F91; A999 A497 A486;
- [004] 018; N- 5A; A999 A511 A486; A999 A771; B9999 B5094 B4977 B4740:
- [005] 018; D00 F20 B- 3A O- 6A; R01894 D00 D60 H- B- 3A O- 6A; A999 A511 A486; A999 A771;
- A02 [001] 018; P0635-R F70 D01; H0011-R;
  - [002] 018; R00444 G0453 G0260 G0022 D01 D12 D10 D26 D51 D53 D58 D83 F70 F93; R00459 G0453 G0260 G0022 D01 D12 D10 D26 D51 D53 D58 D84 F70 F93; H0000; A999 A511 A486; A999 A782; M9999 M2073; P0088
  - -[003] 018; P1592-R F77 D01; A999 A782; A999 A511 A486;
  - [004] 018; P0726 P1934 P0635 F70 D01 D11 D10 D50 E13 E00; H0033 H0011; A999 A511 A486; A999 A782; P0704 P1934 P0635 F70 D01 D11 D10 D50 D93 E17 E00;
  - [005] 018; B9999 B5094 B4977 B4740;